

General purpose (Dual digital transistor)

AEC-Q101 Qualified

| Parameter | DTr1 and DTr2 | | |
|------------------|---------------|--|--|
| V _{CEO} | 50V | | |
| I _C | 100mA | | |
| R ₁ | 4.7kΩ | | |

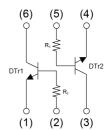
Outline SOT-363 SC-88 UMT6

Features

- 1)Two DTC143T chips in a UMT6 package.
- 2)Mounting possible with UMT3 automatic mounting machines.
- 3)Transistor elements are independent, eliminating interference.
- 4) Mounting cost and area can be cut in half.

•Inner circuit

- (1) DTr1 Emitter
- (2) DTr1 Base
- (3) DTr2 Collector
- (4) DTr2 Emitter
- (5) DTr2 Base
- (6) DTr1 Collector



Application

INVERTER, INTERFACE, DRIVER

Packaging specifications

| Part No. | Package | Package size | Taping code | Reel size (mm) | Tape width (mm) | Basic ordering unit.(pcs) | Marking |
|-----------|-------------------|-----------------|----------------|-------------------|-----------------|---------------------------------|---------|
| UMH3N FHA | SOT-363 (UMT6) | 2021 | TN | 180 | 8 | 3000 | НЗ |

● Absolute maximum ratings (T_a = 25°C)

<For DTr1 and DTr2 in common>

| Parameter | Symbol | Values | Unit |
|------------------------------|---------------------|-------------|------|
| Collector-base voltage | V_{CBO} | 50 | V |
| Collector-emitter voltage | V_{CEO} | 50 | V |
| Emitter-base voltage | | 5 | V |
| Collector current | I _C | 100 | mA |
| Power dissipation | P _D *1*2 | 150 | mW |
| Junction temperature | T _j | 150 | °C |
| Range of storage temperature | T _{stg} | -55 to +150 | °C |

● Electrical characteristics (T_a = 25°C)

<For DTr1 and DTr2 in common>

| Parameter | Cumbal | Conditions | Values | | | Linit | |
|--------------------------------------|--|---|--------|------|------|-------|--|
| Parameter | Symbol Conditions | | Min. | Тур. | Max. | Unit | |
| Collector-base breakdown voltage | | I _C = 50μA | 50 | - | - | V | |
| Collector-emitter breakdown voltage | BV _{CEO} I _C = 1mA | | 50 | - | - | V | |
| Emitter-base breakdown voltage | BV _{EBO} | I _E = 50μA | 5 | - | - | V | |
| Collector cut-off current | I _{CBO} | V _{CB} = 50V | - | - | 500 | nA | |
| Emitter cut-off current | I _{EBO} | V _{EB} = 4V | - | 1 | 500 | nA | |
| Collector-emitter saturation voltage | V _{CE(sat)} | $I_C = 5 \text{mA}, I_B = 250 \mu \text{A}$ | - | - | 300 | mV | |
| DC current gain | h _{FE} | V _{CE} = 5V, I _C = 1mA | 100 | 250 | 600 | - | |
| Input resistance | R ₁ | - | 3.29 | 4.7 | 6.11 | kΩ | |
| Transition frequency | f _T *3 | V _{CE} = 10V, I _E = -5mA, f = 100MHz | - | 250 | - | MHz | |

^{*1} Each terminal mounted on a reference land

^{*2 120}mW per element must not be exceeded.

^{*3} Characteristics of built-in transistor

● Electrical characteristic curves (T_a = 25°C)

<For DTr1 and DTr2 in common>

Fig.1 Grounded Emitter Propagation Characteristics

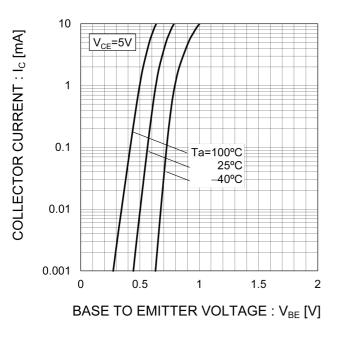


Fig.2 Grounded Emitter Output Characteristics

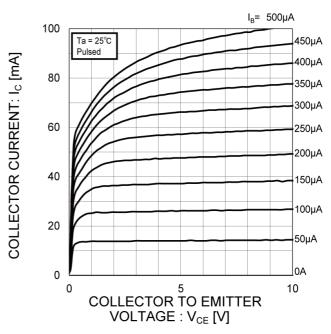


Fig.3 DC Current Gain vs. Collector Current

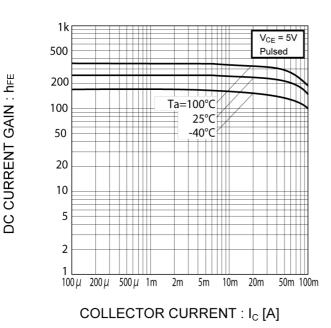
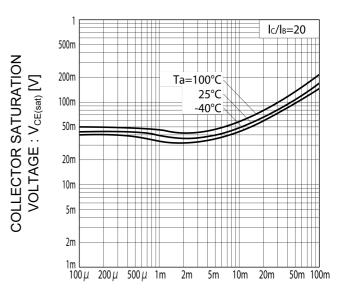
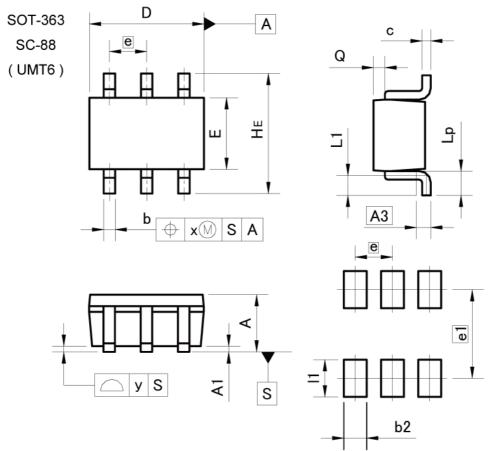


Fig.4 Collector-Emitter Saturation Voltage vs. Collector Current



COLLECTOR CURRENT: Ic [A]

Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

| DIM | MILIM | ETERS | INCHES | | | |
|-----|-------|-------|--------|-------|--|--|
| DIM | MIN | MAX | MIN | MAX | | |
| Α | 0.80 | 1.00 | 0.031 | 0.039 | | |
| A1 | 0.00 | 0.10 | 0.000 | 0.004 | | |
| A3 | 0. | 25 | 0.0 | 0.010 | | |
| b | 0.15 | 0.30 | 0.006 | 0.012 | | |
| С | 0.10 | 0.20 | 0.004 | 0.008 | | |
| D | 1.90 | 2.10 | 0.075 | 0.083 | | |
| E | 1.15 | 1.35 | 0.045 | 0.053 | | |
| е | 0. | 65 | 0.026 | | | |
| HE | 2.00 | 2.20 | 0.079 | 0.087 | | |
| L1 | 0.10 | 0.40 | 0.004 | 0.016 | | |
| Lp | 0.25 | 0.55 | 0.010 | 0.022 | | |
| Q | 0.10 | 0.30 | 0.004 | 0.012 | | |
| х | -> | 0.10 | - | 0.004 | | |
| У | -> | 0.10 | - | 0.004 | | |
| | | | T | | | |
| DIM | MILIM | ETERS | INC | HES | | |

| DIM | MILIMETERS | | INCHES | | |
|------|------------|------|--------|-------|--|
| DIM | MIN | MAX | MIN | MAX | |
| b2 | -2 | 0.40 | - | 0.016 | |
| e1 | 1.55 | | 0.0 | 61 | |
| I1 – | | 0.65 | - | 0.026 | |

Dimension in mm/inches



Notice

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| JAPAN | USA | EU | CHINA |
|---------|---------|------------|--------|
| CLASSⅢ | CLASSII | CLASS II b | ОГУООШ |
| CLASSIV | | CLASSⅢ | CLASSⅢ |

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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